



Final Product Change Notification

201912002F01

Issue Date: 31-Dec-2019
Effective Date: 30-Mar-2020

Dear *Product Data*,

Here's your personalized quality information concerning products Mouser Electronics purchased from Nexperia.
 For detailed information we invite you to [view this notification online](#)



Management Summary

Improved BOM of leadless 5/6 pad packages, including die optimization to achieve zero delamination in ATSN (Nexperia Assembly & Test Plant Seremban Malaysia)

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

Improved leadless 5/6 pad packages incl die optimization to achieve zero delamination

Details of this Change

Improved BOM of leadless 5/6 pad packages, including die optimization to achieve zero delamination in ATSN (Nexperia Assembly & Test Plant Seremban Malaysia)

- Where necessary optimized die for legacy leadless packages
- Improved die aspect ratio and bond-pad relocation to improve intrinsic quality for wire-bond process and support zero delamination
- Identical IP used resulting in same performance as existing die
- BOM change for zero delamination performance
- Enhanced mould compound
- Introduced rough PPF inner leadframe
- Changed lead finish from Sn to enhanced NiPdAu (alignment with packages which were released since 2015)
- No change in diffusion fab, assembly location or ordering part number

Why do we Implement this Change

To improve the intrinsic quality

Identification of Affected Products

The changed products can be identified by backward traceability of the product marking date code as well as on the reel and box labels

Product Availability

Sample Information

Samples are available upon request

Samples are available upon request from the Logic sample store Nijmegen The Netherlands

Production

Planned first shipment 30-Mar-2020

Impact

SOT886/1202/1115: No change

SOT1226/1255: No change in fit, function, quality or reliability anticipated. Pads have rounded edges to enhance adhesion/locking. No change on recommended solder footprint

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 30-Jan-2020. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Remarks

- No change in data sheet electrical specification, test limits and distributions
- No assembly location change
- No fab location change
- Outline drawing products with SOT1226 and SOT1255 will show rounded edges on pads. (A new datasheet will be issued)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact Nexperia "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address PCN-Logic@nexperia.com

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.